



Product Change Notification: DSNO-06KMUN607

Date:

10-Aug-2026

Product Category:

16-Bit Microcontrollers, 32-Bit Microcontrollers, 8-Bit Microcontrollers, Analog Multiplexer/Switch ICs, Analog to Digital Converters, CAN Controller, CAN Controller With Integrated Transceiver, Capacitive Touch Sensors, Current And Power Measurement Ics, Digital Signal Controllers, Digital to Analog Converters, Gate Drivers and Motor Drivers, Hybrid Controllers, Interface- Serial Peripherals, Power Management - PWM Controllers, SST Power Amplifiers, Ultrasound Transmitter Pulser ICs, Wireless Modules, Wireless Power And USB-PD Controller

Notification Subject:

CCB 8425 Initial Notice: Qualification of 558-2C31 as a new die attach material for selected various device families available in various packages at NSEB (UTL-1) assembly site.

Affected CPNs:

[DSNO-06KMUN607_Affected_CPN_08102026.pdf](#)

[DSNO-06KMUN607_Affected_CPN_08102026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 558-2C31 as a new die attach material for selected various device families available in various packages at NSEB (UTL-1) assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	UTAC Thai Limited (UTL-1) (NSEB)	UTAC Thai Limited (UTL-1) (NSEB)	No

Wire Material	Au	Au	No
Die Attach Material	8600 (PFAS)	558-2C31 (PFAS-free)	Yes
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	EFTEC-64T	EFTEC-64T	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improved manufacturability by qualifying 558-2C31 as a new die attach material at NSEB (UTL-1) site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: November 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	August 2026					>	November 2026				
Work Week	32	33	34	35	36		45	46	47	48	49
Initial PCN Issue Date		x									
Qual Report Availability											x
Final PCN Issue Date											x

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: August 10, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-06KMUN607_Qualification_Plan.pdf
PFAS Elimination and Die Attach Explanation.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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